



DDR4 DIMM

TE Internal #: 2309408-1

SO DIMM Sockets, Small Outline (SO), Stack Height .157 in [4 mm],

Right Angle Module Orientation, 260 Position, .02 in [.5 mm]

Centerline, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: **Small Outline (SO)**

Stack Height: **4 mm [.157 in]**

Module Orientation: **Right Angle**

Connector System: **Cable-to-Board**

Number of Positions: **260**

[All DDR4 SO DIMM Sockets \(39\)](#)

Features

Product Type Features

DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	260

Electrical Characteristics

DRAM Voltage	1.2 V
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Signal Characteristics

SGRAM Voltage	1.2 V
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Body Features

Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic



Retention Post Location	Both Ends
Ejector Type	Locking
Connector Profile	Low

Contact Features

Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

Mating Alignment Type	Reverse Keying
PCB Mounting Style	Surface Mount
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.5 mm[.02 in]

Dimensions

Stack Height	4 mm[.157 in]
Row-to-Row Spacing	8.2 mm[.322 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

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Packaging Quantity	900
Packaging Method	Tape & Reel

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | [DDR4 DIMM](#)

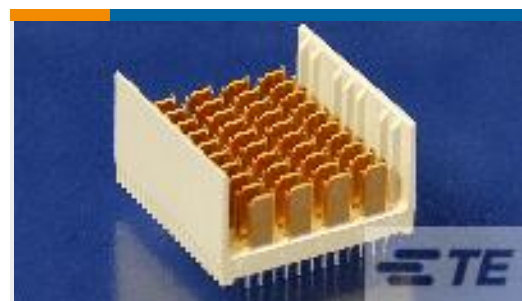
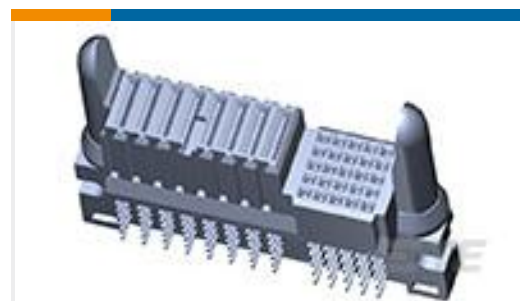
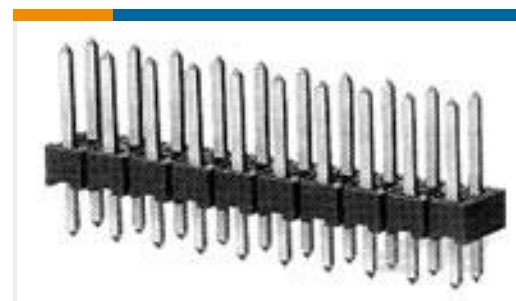


DIMM Sockets(69)



SO DIMM Sockets(39)

Customers Also Bought

TE Part #213850-1
CPC PLUG ASSEMBLY SIZE 23-37TE Part #2-2129710-5
LGA 3647 SocketsTE Part #2336514-1
2MM HM MALE CONNECTOR, COL 8, M2TE Part #2336682-1
2MM HM FEMALE ASSY, COL8TE Part #1469002-1
HM-ZD 4PR HDR 80P 5.2MMTE Part #2-1926739-5
AssyMinipak Hdl25s10pRARectScTE Part #6-146256-3
26 MODII HDR DRST B/A .100CL LFTE Part #CONMHF1-SMD-G-T
U.FL/MHF1 Jack 50 Ohm PCB Surface Mount

Documents

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2309408-1_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309408-1_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309408-1_1.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English

2309408-1

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Module Orientation, 260 Position, .02 in [.5 mm] Centerline, DDR4 DIMM

